SPECIFICATION FOR LCD MODULE

Model No. ____TM162NGHWG

Prepared by: Date: Checked by: **Date:** Verified by: Date: Approved by: Date:

TIANMA MICROELECTRONICS CO., LTD

Rev. 1.0

REVISION RECORD

Date	Ver.	Ref. Page.	Revision No.	Revision It	em

1. General Specifications:

1.1 Display type: FSTN

1.2 Display color*:

Display color: White Background: Dark Blue

1.3 Polarizer mode: Transmissive/Negative

1.4 Viewing Angle: 6:00

1.5 Driving Method: 1/16 Duty 1/5 Bias

1.6 LCD Operation Voltage: 4.8V

1.7 V_{DD} : 5.0V

1.8 Backlight: Without

1.9 Controller: NT7603H-BDT01

1.10 Data Transfer: 8-Bit Parallel Date Input

1.11 Operating Temperature: -20----+50

Storage Temperature: -30----+80

1.12 Outline Dimensions: Refer to outline drawing on next page

1.13 Dot Matrix: 16 Characters × 2Lines

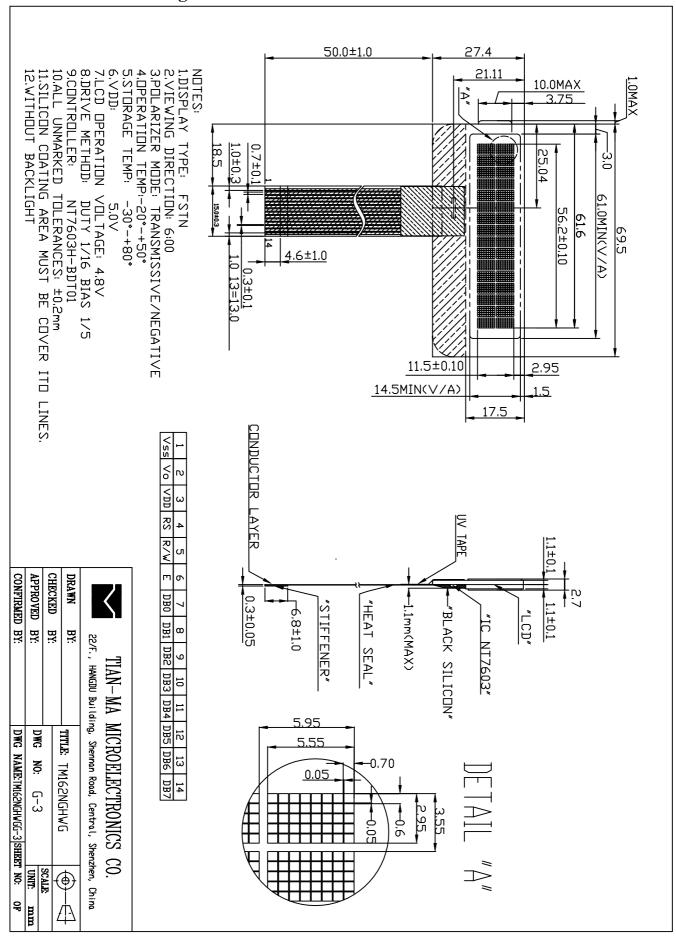
1.14 Dot Size: $0.55 \times 0.65 \text{ (mm)}$

1.15 Dot Pitch: $0.60 \times 0.70 \text{ (mm)}$

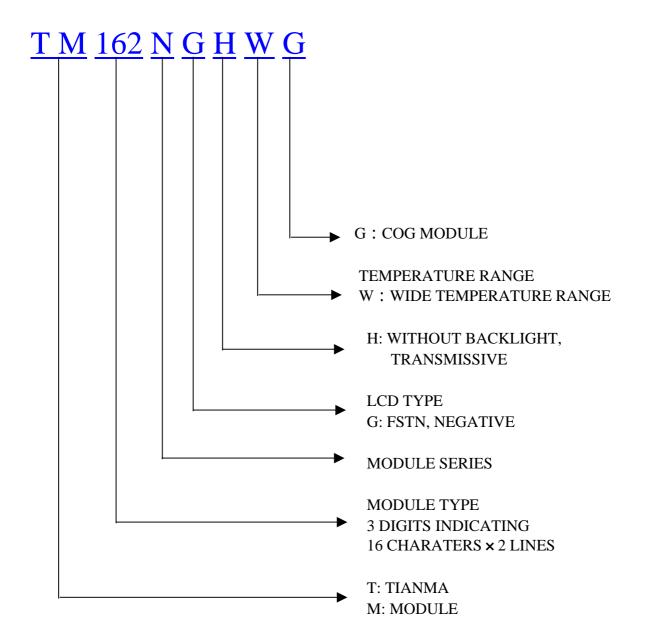
1.16 Weight: 10g (Approx)

^{*} Color tone is slightly changed by temperature and driving voltage.

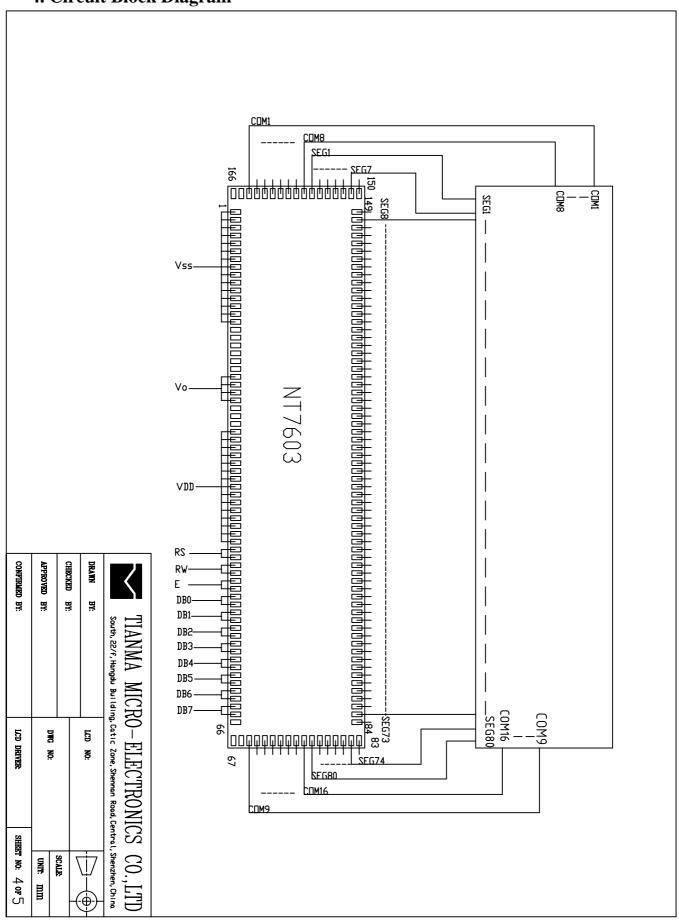
2. Outline Drawing



3. LCD Module Part Numbering System



4. Circuit Block Diagram



5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit	Remark
Power Supply Voltage	V _{DD} - V _{SS}	-0.3	7.0	V	
LCD Driving Voltage	V_{LCD}	-0.3	13.0	v	
Operating Temperature Range	T_{OP}	-20	+50		No
Storage Temperature Range	T_{ST}	-30	+80		Condensation

6. Electrical Specifications and Instruction Code

6.1 DC characteristics

Iten	n	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage (Logic)		V _{DD} - V _{SS}	4.75	5.0	5.25	V
Supply V (LCD D	•	VLCD	-	4.8	5.0	V
Input	High	V _{IH} (V _{DD} =5.0)	$0.8\mathrm{V}_\mathrm{DD}$	ı	$V_{ m DD}$	V
Signal Voltage	Low	V_{IL} (V_{DD} =5.0)	-0.3	1	$0.2V_{DD}$	V
Supply c (Log		I_{DD} (V_{DD} - V_{SS} =5.0)	-	1.5	2.5	mA
Supply c		$ m I_{EE}$	-	-	5.5	mA

6.2 Interface Signals

Pin No.	Symbol	Level	Function
1	V_{SS}	-	GND(0V)
2	Vo	-	CONTRAST ADJUSTMENT
3	$ m V_{DD}$	-	VCC(+5.0V ± 5%)
4	RS	H/L	REGISTER SELECT SIGNAL
5	R/W	H/L	READ/WRITE SELECTION
6	Е	H,H→L	ENABLE SIGNAL
7	DB0	H/L	DATA BIT 0
8	DB1	H/L	DATA BIT 1
9	DB2	H/L	DATA BIT 2
10	DB3	H/L	DATA BIT 3
11	DB4	H/L	DATA BIT 4
12	DB5	H/L	DATA BIT 5
13	DB6	H/L	DATA BIT 6
14	DB7	H/L	DATA BIT 7

6.3 AC Characteristics

AC Characteristics (continued)

Read Cycle (VDD = 3.0V, GND = 0V, TA = $25^{\circ}C$)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Conditions
tcyce	Enable Cycle Time	500	-	-	ns	Figure 1
twhe	Enable "H" Level Pulse Width	300	-	-	ns	Figure 1
tre, tre	Enable Rising/Falling Time	-	-	25	ns	Figure 1
tas	RS, R/W Setup Time	60 ¹	-	-	ns	Figure 1
		100 ²				
tan	RS, R/W Address Hold Time	10	-	-	ns	Figure 1
trd	Read Data Output Delay	-	-	190	ns	Figure 1
tdhr	Read Data Hold Time	20	-	-	ns	Figure 1

Write Cycle (VDD = 3.0V, GND = 0V, Ta = $25^{\circ}C$)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Conditions
tcyce	Enable Cycle Time	500	-	-	ns	Figure 2
twhe	Enable "H" Level Pulse Width	300	-	-	ns	Figure 2
tre, tre	Enable Rising/Falling Time	-	-	25	ns	Figure 2
tas	RS, R/W Setup Time	60 ¹	-	-	ns	Figure 2
		100 ²				
tah	RS, R/W Address Hold Time	10	-	-	ns	Figure 2
tos	Data Output Delay	150	-	-	ns	Figure 2
tohw	Data Hold Time	10	-	-	ns	Figure 2

Notes: 1: 8-bit operation mode

2: 4-bit operation mode

Power Supply Conditions Using Internal Reset Circuit

 $(VDD = 3.0V, GND = 0V, TA = 25^{\circ}C)$

Symbol	Parameter	Min.	Тур.	Max.	Unit	Conditions
tron	Power Supply Rising Time	0.1	-	10	ms	Figure 3
toff	Power Supply OFF Time	1	-	-	ms	Figure 3

Timing Waveforms

Read Operation

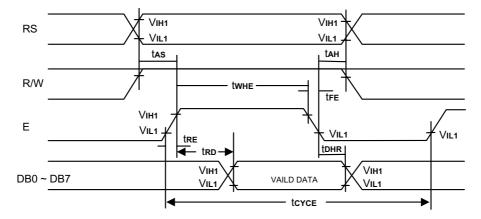


Figure 1. Bus Read Operation Sequence (Reading out data from NT7603 to 8-bit MPU)

Write Operation

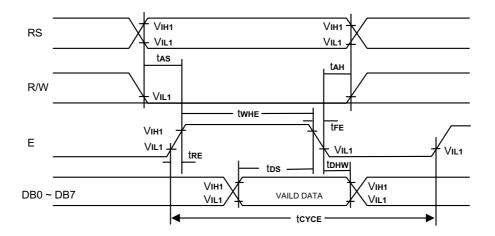


Figure 2. Bus Write Operation Sequence (Writing data from 8-bit MPU to NT7603)

Interface Signals with Segment Driver LSI



Figure 3. toff stipulates the time of power OFF for instantaneous Power supply to or when power supply repeats ON and OFF

6.4 Instruction Code

					High	er 4-bit	(D4 to	D7) of (Characte	r Code	(Hexa	decimal)				
		0	1	2	3	4	5	6	7	8	9	Α	В	С	D	Е	F
	0	CG RAM (1)					::::	•	::: ·					::			
	1	CG RAM (2)			1							:::		#-	<u></u>		
	2	CG RAM (3)		::	•			<u> </u> :::				!	· ‡ .	!!!!	.:: [†]		
	3	CG RAM (4)			:		::	: <u></u> .	: <u>:</u> .				r:	::-	===	∷ .	::-::
	4	CG RAM (5)							₩.			٠.		 	-		:::
	5	CG RAM (6)		:: <u>:</u> :	:		 !	::::	Ii			#	:				
	6	CG RAM (7)					.	#"	I:								:-
lexadecimal)	7	CG RAM (8)		:	:			===	i.;;			:::		.:: :	••••		
racter Code (F	8	CG RAM (1)		K			×	ŀ	×			•	:::	-#-	Ņ	.j	:
Lower 4-bit (D0 to D3) of Character Code (Hexadecimal)	9	CG RAM (2)				1	•	i	: !			•:::	•	ŀ		[
ver 4-bit (D0	Α	CG RAM (3)		: ∳:	::		::::					 .		i i	Ŀ·		
Low	В	CG RAM (4)			:	K		l:	•			:	::			×	
	С	CG RAM (5)		:								† ::	:: <u>:</u> :		:::	₩	
	D	CG RAM (6)						m	:				.::	••••	i	###	
	E	CG RAM (7)		::				!"							•.••		
	F	CG RAM (8)		•••				: <u></u> :	: :-			•:::	`!	~:			

6.5 Instruction Set

Instruction Set

l					C	ode					Function	Executio time (max)
Instruction	RS	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0		(fosc = 250KHz)
Display Clear	0	0	0	0	0	0	0	0	0	1	Clear entire display area, Restore display from shift, and load address counter with DD RAM address 00H.	1.64ms
Display/ Cursor Home	0	0	0	0	0	0	0	0	1	*	Restore display from shift and load address counter with DD RAM address 00H.	1.64ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Specify direction of cursor movement and display shift mode. This operation takes place after each data transfer (read/write).	40μs
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	Specify activation of display (D) cursor (C) and blinking of character at cursor position (B).	4 0μs
Display/ Cursor Shift	0	0	0	0	0	1	S/C	R/L	*	*	Shift display or move cursor.	40μs
Function Set	0	0	0	0	1	DL	N	F	*	*	Set interface data length (DL), number of display line (N), and character font (F).	40μs
RAM Address Set	0	0	0	1			A	CG			Load the address counter with a CG RAM address. Subsequent data access is for CG RAM data.	40μs
DD RAM Address Set	0	0	1				ADD				Load the address counter with a DD RAM address. Subsequent data access is for DD RAM data.	40μs
Busy Flag/ Address Counter Read	0	1	BF				AC				Read Busy Flag (BF) and contents of Address Counter (AC).	1μs
CG RAM/ DD RAM Data Write	1	0				Write	data				Write data to CG RAM or DD RAM.	40μs
CG RAM/ DD RAM Data Read	1	1			Read data						Read data from CG RAM or DD RAM.	40μs
	S = D = C = S/C = R/L = DL = N = E = BF = E = E = E = E = E = E = E = E = E =	= 1 : Dis = 1 : Dis = 1 : Cu = 1 : Cu = 1 : Sh = 1 : Sh = 1 : Du = 1 : 5x = 1 : Int	crement splay Sh splay On irsor Disirsor Blin ifft Displaift Righ Bit ial Line 10 dots ernal Opeady for	nift On n splay Or nk On lay t	ı	S/¢ R/ DL N	C = 0:1 L = 0:5 . = 0:4 = 0:5 = 0:5	Move C Shift Lef -Bit Signal Li	ursor ft		DD RAM : Display Data RAM CG RAM : Character Generator RAM ACG : Character Generator RAM Address ADD : Display Data RAM Address AC : Address Counter	

Note 1: Symbol "*" signifies an insignificant bit (disregard). Note 2: Correct input value for "N" is predetermined for each model.

7. Optical Characteristics

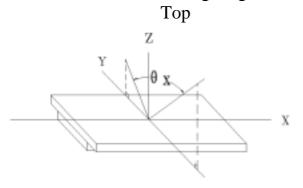
7.1 Optical Characteristics

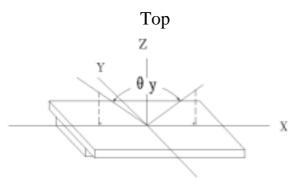
Ta=25

Item		Symbol	Con	dition	Min.	Тур.	Max.	Unit
Vioving	Anala	х	C >2	y=0 °	-35		20	Dag
Viewing A	Angie	у	Cr≥2	x=0 °	-30)	30	Deg
Contrast 1	Ratio	Cr		=0 °	4.0	1	-	
Response	Turn on	T_{on}	x=	x=0 ° y=0 °		1	250	ma
Time	Turn off	$T_{ m off}$	y=	=0 °	-	-	250	ms

7.2 Definition of Optical Characteristics

7.2.1 Definition of Viewing Angle



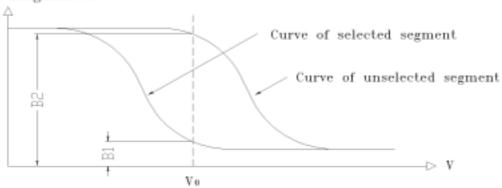


Bottom

Bottom

7.2.2 Definition of Contrast Ratio





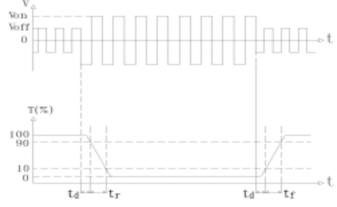
unselected state brightness Contrast Ratio = B2/B1selected state brightness

Measuring Conditions:

1) Ambient Temperature: 25

2) Frame frequency: 64Hz

7.2.3 Definition of Response time



Turn on time: $t_{on} = t_d + t_r$

Turn off time: $t_{off} = t_d + t_f$

Measuring Condition:

1) Operating Voltage: 4.8V

2) Frame frequency: 64Hz

8. Reliability

8.1 Content of Reliability Test

Ta=25

No.	Test Item	Content of Test	Test condition
1	High Temperature	Endurance test applying the high	80
	Storage	storage temperature for a long time	240H
2	Low Temperature	Endurance test applying the low	-30
	Storage	storage temperature for a long time	240H
		Endurance test applying the	
3	High Temperature	electric stress (voltage & current)	50
	Operation	and the thermal stress to the	240H
		element for a long time	24011
	Low Temperature	Endurance test applying the	-20
4	Operation	electric stress under low	240H
	o p o sum o s	temperature for a long time	
_	High Temperature	Endurance test applying the high	40
5	/Humidity Storage	temperature and high humidity	95%RH
	<i>y</i> &	storage for a long time	240H
		Endurance test applying the low	
	Temperature	and high temperature cycle	-30 /80
6	Cycle	-30 25 80 25 30min 5min 30min 5min	
	Cycle		10 cycles
		1 cycle	
	Vibration Test	Endurance test applying the	10Hz~500Hz,
7	(package state)	Endurance test applying the vibration during transportation	100m/s^2 ,
	(package state)	vioration during transportation	120min
	Shock Test	Endurance test applying the shock	Half- sine wave,
8	(package state)	during transportation	300m/s^2 ,
	(Package state)	<u> </u>	18ms
	Atmospheric	Endurance test applying the	25kPa
9	Pressure Test	atmospheric pressure during	25ki a 16H
		transportation by air	1011

8.2 Failure Judgment Criterion

Criterion			T	est l	Iter	n N	0.			Failure Judgement Criterion
Item	1	2	3	4	5	6	7	8	9	randre Judgement Criterion
Basic Specification	1	1	1	1	1	7	1	√	√	Out of the basic Specification
Electrical specification	V	1	1	1	1					Out of the electrical specification
Mechanical Specification							1	√		Out of the mechanical specification
Optical Characteristic	V	1	1	1	1	V			√	Out of the optical specification
Note	Fo	For test item refer to 8.1								
Remark		Basic specification = Optical specification + Mechanical specification								

9. QUALITY LEVEL

Examination or Test	At Ta=25 (unless otherwise stated)	Inspection				
		Min.	Max.	Unit	IL	AQL
External Visual Inspection	Under normal illumination and eyesight condition, the distance between eyes and LCD is 25cm.	See Appendix A			II	Major 1.0 Minor 2.5
Display Defects	Under normal illumination and eyesight condition, display on inspection.	See Appendix B		II	Major 1.0 Minor 2.5	

Note: Major defects: Open segment or common, Short, Serious damages, Leakage

Miner defects: Others

Sampling standard conforms to GB2828

10. Precautions for Use of LCD Modules

- 10.1 Handling Precautions
- 10.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 10.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 10.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 10.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 10.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 10.1.6 Do not attempt to disassemble the LCD Module.
- 10.1.7 If the logic circuit power is off, do not apply the input signals.
- 10.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - a. Be sure to ground the body when handling the LCD Modules.
 - b. Tools required for assembly, such as soldering irons, must be properly ground.
 - c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
 - d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

- 10.2 Storage precautions
- 10.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 10.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature: $0 \sim 40$

Relatively humidity: 80%

- 10.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- 10.3 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.

Appendix A

Inspection items and criteria for appearance defects

Items	Contents	Criteria				
Leakage		Not permitted				
Rainbow		According to the limit specimen				
Polarizer	Wrong polarizer attachment	Not permitted				
	Bubble between	Not counted		Max. 3 defects allowed		
	polarizer and glass	φ<0.3mm	0.3mm \$\phi\$ 0.51		mm	
	Scratches of polarizer	According to the limit specimen				
Black spot (in viewing area)	٥	Not counted	Max	Max. 3 spots allowed		
		X<0.2mm			Max. 3	
		X=(a+b)/2			spots (lines)	
Black line (in viewing area)	0 0	Not counted	Max. 3 lines allowed		allowed	
		a<0.02mm	0.021	mm a 0.05mm b 2.0mm		
Progressive cracks		Not permitted				

Appendix B

Inspection items and criteria for display defects

Items		Contents	Criteria			
Open segment or open common		Not permitted				
Short		Not permitted				
Wrong viewing angle		Not permitted				
Contrast radio uneven		According to the limit specimen				
Crosstalk		According to the limit specimen				
Pin holes and cracks in segment (DOT)	-1 -D	Not counted	Max.3 dots allowed			
		X<0.1mm	0.1mm X 0.2mm			
		X=(a+b)/2	Max.3 dots			
		Not counted	Max.2 dots allowed	allowed		
		A<0.1mm	0.1mm A 0.2mm D<0.25mm			
Black spot (in viewing area)	pot	Not counted	Max.3 spots allowed			
		Ì	X<0.1mm	0.1mm X 0.2mm	1	
		X=(a+b)/2	Max.3 spots			
Black line (in viewing area)		Not counted	Max.3 lines allowed	(lines) allowed		
		a<0.02mm	0.02mm a 0.05mm b 0.5mm			

Appendix BInspection items and criteria for display defects (continued)

Items	Content	Criteria			
Transfor- mation of segment		Not counted	Max. 2 defects allowed		
		x < 0.1mm	0.1mm x 0.2mm		
		x=(a+b)/2			
				Max.3	
		Not counted	Max. 1 defects allowed	defects allowed	
		a < 0.1mm	0.1mm a 0.2mm D>0		
		Max.2 defects allowed 0.8W a 1.2W			
		a=measured value of width W=nominal value of width			